Bill of Materials

	SCM	SCC	Remarks
Die Attach	Ablestik 8290	Ablestik 8290	Same BOM
Wire type	Gold MKE UR2	Gold MKE UR2	
Mold Compound	Sumitomo G770	Sumitomo G770	
Lead Finish	Matte Sn	Matte Sn	

Amplifiers Power Management Processors DSP RF Communications MEMS Converters

Qualification Results Summary for Multi Die in LFCSP Package at STATS ChipPAC China (SCC)

QUALIFICATION RESULTS

Test	Specification	Sample Size	Result
Highly Accelerated Stress Test (HAST)*	JEDEC *JESD22-A110*	**3 x 77**	**PASS**
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	**3 x 77**	**PASS**
Autoclave (AC)*	JEDEC *JESD22-A102*	**3 x 77**	**PASS**
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	**3 x 11**	**PASS**
High Temperature Storage Life (HTSL)	JEDEC *JESD22-A103*	**1 x 77**	**PASS**
Field Induced Charged Device Model (FICDM)	JEDEC *JESD22-C101*	**3/Voltage**	**PASS ±750V**

*Preconditioned per JEDEC/IPC J-STD-020